



# Available Reverse engineering report list

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IC Features	Item	Process	Description	Report
Power DC/DC	TI TPS82671	CMOS 0.22um 1P4M	600mA, DC/DC step-down power supply intended for low-power applications – Die size: 0.87mm*1.24mm=1.08mm <sup>2</sup>	Full chip analysis
Power DC/DC	TI TPS62671	CMOS 0.22um 1P4M	high-frequency synchronous step-down dc-dc converter optimized for battery-powered portable applications. Die size: 0.87mm*1.24mm=1.08mm <sup>2</sup>	Full chip analysis
Power DC/DC	TI TPS61280	CMOS 0.25um 1P 3M+RDL	Low-, Wide- Voltage Battery Front-End DC/DC Converter Single-Cell Li-Ion, Ni-Rich, Si-Anode Applications Die size : 1.63mm*1.63mm	Analog circuit analysis
Power DC/DC	Richtek RT7239	CMOS 0.25um 1P3M	synchronous step-down DC-DC converter with advanced constant-on time (ACOT™) mode control. Die size : 1.56mm*1.68mm	Analog part analysis
Power AC/DC	BCD GP 360H1M	BCD 0.6um 1P1M	AC-DC power supply controller for battery charger and adapter applications, It can meet less than 10Mw standby power for "super" charger. Die size : 1.70mm * 1.67mm	Full chip analysis
Power Bipolar	MPS – MP6507	CMOS 0.5um 1P 2M	2.7V-to-15V, 700mA, Bipolar Stepper-Motor Driver with Integrated MOSFETs. Die size : 1.4mm*1.51mm	Analog circuit analysis
Power ADC	ADI – AD7794	CMOS 0.35um 1P3M	low power, low noise, complete analog front ends for high precision measurement applications. They contain a low noise, 24-/16-bit Σ-Δ ADC with six differential inputs.	Analog circuit analysis
GaNFast™ Power IC	Navitas NV6134A	CMOS 0.15um 1P5M	Loss-Less Current Sensing GaN Senset™ Technology Die size: 1.52mm*0.62mm	Full chip analysis
Power	TI BQ27545	CMOS 0.25um 1P4M	Single Cell, Pack Side, Impedance Track Fuel Gauge Die size: 2.56mm*1.9mm	Analog part photo
Power	AmbiQ mirco AM1805	CMOS 0.35um 1P3M	Real-Time Clock with Power Management Family provides a groundbreaking combination of ultra-low power coupled with a highly sophisticated feature set.	Analog part analysis
Power	TI BQ27441	CMOS 0.18um 1P4M	Battery Fuel Gauge offer fuel gauging solution for single series cell Li-ion battery packs. Die size: 1.56mm*1.51mm	Partial chip analysis <a href="http://192.168.11.6">\\192.168.11.6</a> 業務
Power	TI BQ24195	CMOS 0.25um 1P4M	I2C Controlled / 4.5A Single Cell USB/Adapter Charger With at 2.1A Synchronous Boost Operation FEATURES Die size : 2.63mm * 2.61mm = 6.86 mm <sup>2</sup>	Full chip analysis
Power	TI – THS6212	BCD 0.8um 1P 3M	Differential line-driver amplifier with a current-feedback architecture. support transmissions of 14.5-dBm line power up to 30 MHz. Die size : 1.783mm ×1.956mm	Analog circuit analysis
Power	TI- TPS65651	CMOS 0.18um 1P4M	TPS65651 Triple-Output AMOLED Display Power Supply , Single-Wire Digital Interface for Programming. Die size : 1.63mm ×1.63mm	Analog circuit analysis <a href="http://192.168.11.6">\\192.168.11.6</a> 業務
Power	TI- LP5907	CMOS 0.18um 1P4M	LP5907 250-mA Ultra-Low-Noise, Low-IQ LDO, RF and analog circuits, high PSRR, low quiescent current, and low line or load transient response figures. Die size : 0.58mm ×0.58mm	Full chip analysis
Power	TI – TPS62088	CMOS 0.13um 1P4M	Tiny 6-pin 3-A Step-Down Converter in 1.2-mm x 0.8-mm WCSP. Die size : 1.15mm ×0.75mm	Full chip analysis
Power	Onsemi NCP137	CMOS 0.25um 1P4M	700 mA, Very Low Dropout Bias Rail CMOS Voltage Regulator. Die size : 1.15mm ×0.75mm	Full chip analysis
Power	SGMICRO SGM40658	CMOS 0.22um 1P3M+RDL	High-Current Over-Voltage Protector (5.97V) Die size : 1.26mm ×1.79mm	Partial circuit analysis



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IC Features	Item	Process	Description	Report
Power	MPS MP1470	CMOS 0.35um 1P3M	High-Efficiency, 2A, 16V, 500kHz ,Synchronous, Step-Down Converter Die size : 1.23mm*0.87mm=1.07mm <sup>2</sup>	Full chip photography
Power	PI INN3270 DP1	CMOS 0.35um 1P3M	Off-Line CV/CC QR Flyback Switcher IC with Integrated Primary-Side Switch, Synchronous Rectification, FluxLink Feedback and Constant Power Profile Die size: 1.0mm*1.49mm	Full chip analysis
Power	PI INN3270 DP2	CMOS 0.35um 1P3M	Off-Line CV/CC QR Flyback Switcher IC with Integrated Primary-Side Switch, Synchronous Rectification, FluxLink Feedback and Constant Power Profile	Full chip analysis
Power	Silergy SY8120	CMOS 0.5um 1P2M	High Efficiency Fast Response, 2A, 16V Input Synchronous Step Down Regulator Die size: 0.9mm*1.70mm=1.53mm <sup>2</sup>	Full chip analysis
Power	Fairchild – FAN302	CMOS 0.5um 1P2M	PWM controller significantly simplifies isolated power supply design that requires CC regulation of the output. Die size: 1.611mm*1.286mm	Analog circuit analysis
Power	TI BQ24196	CMOS 0.25um 1P4M	I2C Controlled 2.5A Single Cell USB/Adapter Charger With Narrow VDC Power Path Management and USB OTG Die size : 2.63mm * 2.61mm = 6.86 mm <sup>2</sup>	Full chip analysis
Power	TI LM3646	CMOS 0.25um 1P5M	1.5A Synchronous Boost Converter with Dual High-Side Current Sources and I2CCCompatible Interface Die size : 1.95mm * 1.55mm = 3.02 mm <sup>2</sup>	Analog circuit analysis
Touch	Synaptics - S3202A S3200	CMOS 0.18um 1P5M	Capacitive Touch panel controller Highly Accurate, Responsive 10-Finger Touch.	AFE,ADC circuit analysis
Touch	Goodix- GT967,GT968,GT927,GT928,GT915	CMOS 0.11um 1P6M	Capacitive Touch panel controller , support On-cell, PG, GG, GF, OGS , cover & sensor , 4"~10.1" , 5~10 points true touch Die size: 1.2mm*2.97mm	AFE circuit analysis
Touch	Mstar MSG2133A	CMOS 0.13um 1P7M	Touch screen controller Die size :2.60mm * 2.20mm	Partial circuit analysis Photography
Touch	Broadcom BCM5976	CMOS 0.13um 1P6M	Touch screen controller by Broadcom use to Apple iphone 5 / iPad mini / Macbook Air. Die size : 3.86mm * 3.23mm	Partial circuit analysis Photography
Touch	Synaptics S3528A,S5050A, S5100A	CMOS 0.18um 1P5M	The Synaptics S3528A is a touch screen controller found in the HTC HTC6525L, (Die mark : " 2013 T1327A ") Die size : 4.02mm*3.64mm	AFE circuit analysis
Touch	Goodix- GT967,GT968,GT927,GT928,GT915	CMOS 0.11um 1P6M	Capacitive Touch panel controller , support On-cell, PG, GG, GF, OGS , cover & sensor , 4"~10.1" , 5~10 points true touch Die size: 1.2mm*2.97mm	AFE circuit analysis
TDDI	Synaptics TD4191	CMOS 0.11um 1P6M	Touch and display driver integration (TDDI) delivers best-in-class capacitive sensing performance and industry-leading display noise management. Die size : 31.87mm*1.29mm	AFE circuit analysis
TDDI	Focaltech FT8606	CMOS 0.11um 1P6M	IDC integrates driver controller , support a-Si TFT LCD HD. Die size : 32.0mm*1.0mm	AFE circuit analysis
TDDI	Focaltech FT8716	CMOS 90nm 1P6M	IDC integrates driver controller , support a-Si TFT LCD HD. Die size : 32.0mm*1.0mm	LCD driver & AFE circuit analysis and ESD imaging
TDDI	Nova- NT36625	CMOS 80nm 1P7M	TDDI Reverse report : Nova NT36625 TP Die size : 32.01mm ×1.00mm	AFE circuit analysis
ADDI	NA TC2200	CMOS 0.13um 1P6M	ADDI driver ic reverse report Die size: 1.27mm*32.5mm	Chip reverse analysis



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IC Features	Item	Process	Description	Report
HDMI/MHL Receiver	EPMI – EP9555E	CMOS 0.18um 1P5M	Low Power 3-Port HDMI/MHL Receiver with Scaler and CCIR 656 Output Die size : 2.84mm*2.68mm	Analog circuit analysis
Laser drivers Transceivers	SEMTECH GN1190	CMOS 65nm 1P7M	GN1190 is 4 channel VCSEL array driver 1.0Gbps to 14.5Gbps. Use with GN1090 quad TIA. Die size : 1.73mm*0.84mm	AFE net list extraction.
ARM Cortex-M4 MCU	STM STM32L476	CMOS 90nm 1P7M	Ultra-low-power with FPU ARM Cortex-M4 MCU 80 MHz with 1Mbyte Flash, LCD, USB OTG Die size : 4.38mm*3.73mm	Analog part circuit
ETC 5.8G	SKYRELAY ET6602	CMOS 0.18um 1P5M	ETC 5.8G solution Die size : 1.63mm*1.29mm	Full chip analysis
Fast charge 3.0 / 4.0 for USB ,Type-C	Weltrend WT6615F	CMOS 0.18um 1P5M	Die Size: 2714 um x 2401um (w/i scribe line) WT6615F that supported USB3.0 and QUALCOMMQuick ChargeTM 3.0 / 4.0 for USB ,Type-C Charging applications.Circuit Analysis Report	Analog circuit analysis
LED driver	Richtek RT8487	CMOS 0.25um 1P2M	High Efficiency BCM LED Driver Controller for High Power Factor Offline Applications. Die size : 0.70mm*0.68mm	Full chip analysis
LED driver	Chinaasic MW1817D	CMOS 0.18um 1P2M	A three-channel LED drive control chip with single-line zero-code SID data protocol Die size: 0.33mm*0.35mm	Full chip analysis
AMP Ethernet	Gennum GN1068	CMOS 0.18um 1P6M	GN1068 4-16Gbps Rate Selectable Transimpedance Amplifier. 10 Gigabit Ethernet / Serial Data Systems up to 14.5Gbps . Die size : 1.16mm*0.85mm	Full chip analysis
Wireless & RF	RFMD – RFMD2080	CMOS 0.13um 1P6M	45MHz To 2700MHz IQ MODULATOR WITH SYNTHESIZER / VCO AND BASEBAND INTERFACE. Die size : 2.97mm *3.32mm	Full chip analysis
Ethernet Phyceiver 10/100M	Realtek – RTL8201F	CMOS 0.11um 1P7M	Single-Chip/Port 10/100M Ethernet Phyceiver with Auto MDIX Die size : 0.974mm*1.461mm	Analog circuit analysis
Driver ic Passive Pens	Wacom W4035S	CMOS 0.6um 1P2M	Passive Pens EMR Driver ic. Die size : 2.32mm x1.36mm	Full chip analysis
Test handler	Hitachi NRO7QV001T	CMOS 0.35mm 1P2M	Test handler IC Reverse report. Die size: 8.89mm x 6.91mm	Partial circuit analysis
Sensor Cmos image	CIS PS5268	CMOS 90Nm 1P3M	cmos image sensor. Die size:5mm x 6mm	Partial chip analysis
Driver OVTV	NA SW92501	CMOS 0.15um 1P6M	OVTV Driver IC Reverse report. Die size : 1.22mm x31.9mm	Partial circuit analysis
Light Peak Transceiver	ESI XVR10100	CMOS 65nm 1P7M	Dual 10Gbit/s Optical Transceiver for Light Peak. Die size: 2.25mm*0.90mm=2.03mm <sup>2</sup>	Analog circuit Imaging Annotation
AMOLED structure	Apple iphone5	In-cell 4” - 326ppi	AMOLED panel analysis report iphone size : 123mm*58mm	Panel analysis structure
AMP Transimpedance	SEMTECH NT28L52	CMOS 0.13um 1P6M	Law power TIA 10GBASE-SR Ethernet and Wireless infrastructure. Die size : 1.12mm*0.88mm	Partial circuit analysis



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IC Features	Item	Process	Description	Report
USB3.1 Gen2 Up to 10Gbps	ASMEDIA ASM1562	CMOS 55nm 1P7M	one lane, 2 differential channels SuperSpeedPlus USB3.1 Gen2 Retimer, up to 10Gbps- Die size: 2.1mm*2.1mm	Chip partial analysis
Audio	Realtek ALC5672	CMOS 0.11um 1P6M	Multi-Channel Audio Hub/CODEC with Gen.3 Voice DSP and SounzReal™ Post-Processing for Mobile Devices Die size : 2.842*4.181mm	Analog circuit analysis
Direction driver	STMicroelectronics – VN1160	CMOS 1.5um 1P1M	Direction indicator driver for motorbike. Die size: 2.412mm*2.080mm	Full chip analysis
LCD Driver iSP	Novatek NT60274	CMOS 0.15um 1P4M	NT60274 is a source driver with 966/960/864/726 outputs. supplies integrated-Stream Protocol (iSP) interface for low EMI. 8-bit resolution / 256 gray scale, (1/2 pairs serial data input) Die size: 19.21mm*1.21mm	RX PHY analysis
DDR5 PMIC Solution	Richtek RTQ5132	CMOS 0.18um 1P4M	DDR5 UDIMM & SO-DIMM PMIC Input Voltage Range 4.25V to 5.5V • Three High Efficiency Step-down Converters Die size: 3.66mm *2.65mm	Full chip analysis
High-speed CAN transceiver	Microchip MCP2561/2FD	CMOS 0.35um 1P3M	It serves as an interface between a CAN protocol controller and the physical two-wire CAN bus. device meets the automotive requirements for high-speed (1Mb/s)Die size: 1.83mm*1.33mm	Full chip analysis
Resonant LLC controller	NXP TEA19161T	CMOS 0.25um 1P5M	Digital controller for high-efficiency resonant power supply. Die size: 1.81mm*1.54mm	Full chip analysis
Monolithic integrated circuit Support AOI	Infineon TLE9262	CMOS 0.13um 1P5M	Various CAN-LIN automotive applications as main supply for the microcontroller and as interface for a LIN and CAN bus network including the CAN Partial Networking feature. Die size: 2.24mm*2.05mm	Partial circuit analysis
Power	Silergy SY8388C3	CMOS 0.16um 1P2M+RDL	High Efficiency Fast Response, 8A, 28V Input Synchronous Step Down Regulator. Die Size:2.13*1.81mm	Analog circuit analysis
Thunderbolt™ 4 Retimer Tr	Intel® JHL8040R	CMOS 28nm 1P10M+RDL	Reverse partial Photography: Intel® Thunderbolt™ 4 Retimer Die size:2.37*3.3mm	Partial photography
SAR ADC	IP	CMOS 55nm 1P5M	SAR ADC 14-bit, 2.5MSPS 3.3V Die size: 0.78*0.35mm	Analog circuit analysis
LDO	ETA Solutions ETA5055	CMOS 160nm 1P2M	Ultra-high PSRR, 500mA LDO for RF in DFN1X1-4 and SOT23-5. Die size:0.36*0.36mm	Full chip analysis
Power	Silergy SY8388C	CMOS 160nm 1P2M+RDL	High Efficiency Fast Response, 8A, 28V Input Synchronous Step Down Regulator Reverse report	Partial circuit analysis
TX , RX	TI UCC21530	CMOS 180nm 1P7M	Car PMIC : 5.7kVrms, 4A/6A dual-channel isolated gate driver.	Partial circuit analysis
Battery Monitor	TI BQ76942	CMOS 150nm 1P4M	3-Series to 10-Series High Accuracy Battery Monitor and Protector for Li-Ion, Li- Polymer, and LiFePO4 Battery Packs Reverse report	Partial circuit analysis

